

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"hitachi chemical".asn	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 08:46
L2	0	"hitachi chemical".asn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 08:46
L3	1996	"hitachi chemical".asn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 08:46
L4	1996	3 and ad<"20050225"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 08:47
L5	519	4 and (semiconductor or semi-conductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 08:48
L6	18	5 and (encapsul\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 08:49
S1	752539	semiconductor or semi-conductor	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:06
S2	2197561	knead\$3 or blend\$3 or stir\$4 or blend\$3 or mix\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:11
S3	11198021	@pd<"20030201"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:20
S4	749029	volatile or vaporous or gaseous	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:23
S5	14632	S1 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:25
S6	1180198	vacuum\$3 or suction\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:27

S7	7791	S5 and S6	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:28
S8	1	("5930652").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/15 08:40
S9	14413	(chip adj scale adj packag\$4) or (chip size packag\$4) or csp	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:41
S10	6	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:42
S11	261249	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:43
S12	107	S1 near S11 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:44
S16	1185643	semiconductor or semi- conductor	JPO; DERWENT	ADJ	ON	2008/04/15 09:07
S17	1806059	knead\$3 or blend\$3 or stir\$4 or blend\$3 or mix\$3	JPO; DERWENT	ADJ	ON	2008/04/15 09:07
S18	18309706	@pd< "20030201"	JPO; DERWENT	ADJ	ON	2008/04/15 09:07
S19	218959	volatile or vaporous or gaseous	JPO; DERWENT	ADJ	ON	2008/04/15 09:08
S20	650886	vacuum\$3 or suction\$3	JPO; DERWENT	ADJ	ON	2008/04/15 09:08
S21	7046	(chip adj scale adj packag\$4) or (chip size packag\$4) or csp	JPO; DERWENT	ADJ	ON	2008/04/15 09:08
S22	51276	encapsulat\$3	JPO; DERWENT	ADJ	ON	2008/04/15 09:08
S24	5	S16 near S22 and S17 and S18 and S19	JPO; DERWENT	ADJ	ON	2008/04/15 09:10
S27	196	S16 near S22 and S17 and S18	JPO; DERWENT	ADJ	ON	2008/04/15 09:14
S28	3828	kneading machine	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:14
S29	752539	semiconductor or semi- conductor	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S30	2197561	knead\$3 or blend\$3 or stir\$4 or blend\$3 or mix\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S31	11198021	@pd< "20030201"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S32	749029	volatile or vaporous or gaseous	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S33	14632	S1 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S34	1180198	vacuum\$3 or suction\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S35	7791	S5 and S6	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S36	1	("5930652").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/15 10:15
S37	14413	(chip adj scale adj packag\$4) or (chip size packag\$4) or csp	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15

S38	6	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S39	261249	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S40	107	S1 near S11 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S41	1185643	semiconductor or semi- conductor	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S42	1806059	knead\$3 or blend\$3 or stir\$4 or blend\$3 or mix\$3	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S43	218959	volatile or vaporous or gaseous	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S44	650886	vacuum\$3 or suction\$3	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S45	7046	(chip adj scale adj packag\$4) or (chip size packag\$4) or csp	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S46	51276	encapsulat\$3	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S47	5	S16 near S22 and S17 and S18 and S19	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S48	196	S16 near S22 and S17 and S18	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S49	3828	kneading machine	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S65	2	jp-2001081284-\$.did.	FPRS; JPO; DERWENT	ADJ	ON	2008/04/15 13:33
S66	0	jp-3320354	JPO; DERWENT	ADJ	ON	2008/04/15 13:36
S67	1	jp-3320354-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:36
S68	1	jp-3009027-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:43
S69	0	jp-6-293021-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:45
S70	0	jp-6293021-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:45
S71	0	jp-0293021-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:46
S72	0	jp-293021-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:46
S73	20616	biaxial	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:53
S74	250733	extrusion	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:53
S75	208	S73 near S74	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:53
S76	106	S73 near S74 and S3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:55
S77	0	S73 near S74 and S3	JPO; DERWENT	ADJ	ON	2008/04/15 14:06

S78	79	biaxial near extrusion and @pd<"20030201"	JPO; DERWENT	ADJ	ON	2008/04/15 14:07
S79	0	biaxial near S30 and S31	JPO; DERWENT	ADJ	ON	2008/04/15 14:34
S80	344	biaxial near S42 and @pd<"20020201"	JPO; DERWENT	ADJ	ON	2008/04/15 14:43
S81	415	biaxial near S42 and @pd<"20030201"	JPO; DERWENT	ADJ	ON	2008/04/15 14:43
S82	11	S81 and S19	JPO; DERWENT	ADJ	ON	2008/04/15 14:44
S83	0	jp-6293021-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/16 08:13
S84	0	jp-5104947-\$.did.	JPO; DERWENT	ADJ	ON	2008/04/16 08:14
S85	6945	@pd="19941021"	JPO; DERWENT	ADJ	ON	2008/04/16 08:22
S86	2	jp706293021??did.	JPO; DERWENT	ADJ	ON	2008/04/16 08:24
S87	2	("2543181").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/16 08:42
S88	0	noborakku	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/16 11:49
S89	0	noborakku	US-PGPUB; USPAT; USOCR; JPO; DERWENT	ADJ	ON	2008/04/16 11:49
S90	0	(2002/0195725).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/16 12:18
S91	459	epoxy and resin and (inorganic or silica) and ((semiconductor or semi? conductor) near5 encapsul\$3) and @pd<"20030201"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/16 12:34
S92	0	(10/526008).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/17 06:26
S93	0	("10526008").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/17 06:27
S94	1	("20060017188").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/17 06:29
S95	375	(264/211.21).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 10:23
S96	3	S95 and (semiconductor or semi?conductor)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/22 10:24
S97	1704	((257/780) or (793/794)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/28 05:43

S98	0	S97 and @pd<"2002"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:43
S99	0	257/780 and @pd<"2002"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:44
S100	1704	(257/780).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/28 05:45
S101	631	S100 and @py<"2002"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:45
S102	66	S101 and (refractory or lining or steel\$6 or repair)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:46
S103	18309709	@pd<"20030201"	JPO; DERWENT	ADJ	ON	2008/04/28 05:50
S104	91	S103 and 257/780.ocls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:50
S105	2201692	knead\$3 or blend\$3 or stir\$4 or blend\$3 or mix\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/28 05:52
S106	14481	(chip adj scale adj packag\$4) or (chip size packag\$4) or csp	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/28 05:52
S107	1188706	semiconductor or semi- conductor	JPO; DERWENT	ADJ	ON	2008/04/28 05:52
S108	64	S104 and (S107 or S106 or S105)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:52
S109	751035	volatile or vaporous or gaseous	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/28 05:54

S110	0	S108 and S109	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:54
S111	755432	semiconductor or semi-conductor	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/28 05:54
S112	11198021	@pd< "20030201"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/28 05:54
S113	262215	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/28 05:54
S114	107	S111 near S113 and S105 and S112 and S109	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/28 05:54
S115	0	S114	JPO; DERWENT	ADJ	ON	2008/04/28 05:54
S116	0	S108 and S115	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:54
S117	4	((("0000793") or ("0000794")). PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/28 05:55
S118	0	(257/793or257/794).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/28 05:57
S119	1036	((257/793) or (257/794)). CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/28 05:57
S120	907	S119 and (S112 or S107 or S113 or S105)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 05:59
S121	36	S120 and S109	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/28 06:00

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